

Amendments to the Claims:

This listing of claims replaces all prior versions and listings of claims in the application:

Listing of Claims:

1-9. canceled

10. (new) A method of manufacturing a multilayer substrate, the method comprising:

preparing a laminated sheet including a resin core section having a first surface and a second surface, and a positioning section formed to penetrate through the core section from the first surface to the second surface of the core section;

coating an inner wall of the positioning section with a metal material;

laminating a conductive film on each of the first surface and the second surface of the laminated sheet via an insulating film;

removing the conductive film and the insulating film from a region corresponding to the positioning section to expose the inner wall of the positioning section;

determining position information about the inner wall of the positioning section and using the position information as reference information to determine a position of the conductive film; and

subsequently patterning the conductive film to form a wiring layer.

11. (new) The method of claim 10, wherein patterning the conductive film includes patterning both of the conductive film laminated on the first surface of the laminated sheet and the conductive film laminated on the second surface of the laminated sheet.

12. (new) The method of claim 10, wherein patterning the conductive film includes using the position of the inner wall of the positioning section as a reference.

13. (new) The method of claim 10, wherein patterning the conductive film includes patterning a resist using an exposure mask, and etching the conductive film via the patterned resist, wherein the positioning section is used as a reference for positioning the exposure mask.

14. (new) The method of claim 13, wherein determining the position information includes identifying a plurality of points of the inner wall of the positioning section, assuming a cross-section of the positioning section to be circular, and calculating a position of a center point of the positioning section based on the positions of the plurality of points, and positioning the exposure mask includes using the position of the center point as a reference.

15. (new) The method of claim 10, wherein determining the position information includes identifying a plurality of points of the inner wall of the positioning section, assuming a cross-section of the positioning section to be circular, and calculating a position of a center point of the positioning section based on the positions of the plurality of points, and patterning the conductive film includes using the position of the center point as a reference.

16. (new) The method of claim 10, wherein removing the conductive film and the insulating film includes providing an exposed portion by removing the conductive film in a region overlapping the positioning section and irradiating laser light onto the insulating film through the exposed portion to expose the inner wall of the positioning section.

17. (new) The method of claim 10, further comprising coating a periphery of the positioning section in each of the first surface and second surface of the core section with a protection portion made of a metal material, and wherein a laser is irradiated onto the insulating film filled in the positioning section and onto the protection portion to expose the inner wall of the positioning section.

18. (new) A method of manufacturing a multilayer substrate, the method comprising:
preparing a laminated sheet including a first insulating film having a first surface and a second surface each made of a resin, a first wiring layer formed on the first surface of the first insulating film, a second wiring layer formed on the second surface of the first insulating film, and a positioning

section formed to penetrate the first insulating film from the first surface to the second surface of the first insulating film, and the positioning section having an inner wall coated with a metal material;

laminating a first conductive film on the first surface of the first insulating film via a second insulating film,

laminating a second conductive film on the second surface of the first insulating film via a third insulating film;

exposing the inner wall of the positioning section by removing the first and second conductive films in respective regions overlapping the positioning section, and by removing a resin material filled in the positioning section;

forming a third wiring layer by patterning the first conductive film by using a position of the inner wall of the positioning section as a reference; and

forming a fourth wiring layer by patterning the second conductive film by using the position of the inner wall of the positioning section as a reference.

19. (new) The method of claim 18, wherein removing the resin material includes irradiating laser light on the resin material.

20. (new) The method of claim 18, wherein forming the third wiring layer includes applying a resist to the first conductive film, patterning the resist with an exposure mask by using the positioning section as a reference to position the exposure mask, and etching the first conductive film through the patterned resist.

21. (new) The method of claim 20, wherein using the positioning section as a reference includes identifying positions of a plurality of points of the inner wall of the positioning section, assuming the shape of the position section to be circular in a plan view, and calculating a position of a center point of the positioning section based on the positions of the plurality of points, and wherein positioning the exposure mask uses the position of the center point as a reference.

22. (new) The method of claim 18, wherein forming the fourth wiring layer includes applying a resist to the second conductive film, patterning the resist with an exposure mask by using the positioning

section as a reference to position the exposure mask, and etching the second conductive film through the resist.

23. (new) The method of claim 22, wherein using the positioning section as a reference includes identifying positions of a plurality of points of the inner wall of the positioning section, assuming the shape of the positioning section to be circular in a plan view, and calculating a position of a center point of the positioning section based on the positions of the plurality of points, and wherein positioning the exposure mask uses the position of the center point as a reference.

24. (new) The method of claim 18, further comprising coating a periphery of the positioning section in each of the first surface and second surface of the first insulating film with a protection portion made of a metal material, and wherein exposing the inner wall of the positioning section includes irradiating a laser onto the resin material filled in the positioning section and onto the protection portion.